SEMIKRON

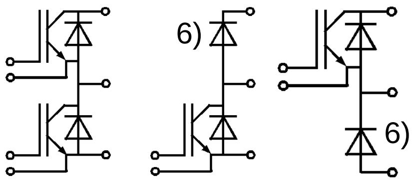
Absolute Maximum Ratings Symbol	Conditions [1]	Values		Units
V_{CES}		1700		V
V_{CGR}	R_{GE} = 20 kΩ	1700		V
I_C	T_{case} = 25/80 °C	220 / 150		A
I_{CM}	T_{case} = 25/80 °C; t_p = 1 ms	440 / 300		A
V_{GES}		± 20		V
P_{tot}	per IGBT, T_{case} = 25 °C	1250		W
T_j, (T_{stg})		– 40 . . .+150 (125)		°C
V_{isol}	AC, 1 min.	4000		V
humidity	DIN 40 040	Class F		
climate	DIN IEC 68 T.1	40/125/56		
Inverse Diode [8]			"FWD; D1"[6]	
I_F= – I_C	T_{case} = 25/80 °C	150 / 100	230 / 150	A
I_{FM}= – I_{CM}	T_{case} = 25/80 °C; t_p = 1 ms	400 / 300	400 / 300	A
I_{FSM}	t_p = 10 ms; sin.; T_j = 150 °C	1450	2200	A
I^2t	t_p = 10 ms; T_j = 150 °C	10500	24000	A^2s

Characteristics Symbol	Conditions [1]	min.	typ.	max.	Units
$V_{(BR)CES}$	V_{GE} = 0, I_C = 3 mA	≥ V_{CES}	–	–	V
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 10 mA	4,8	5,5	6,2	V
I_{CES}	V_{GE} = 0 } T_j = 25 °C	–	–	1,5	mA
	V_{CE} = V_{CES} } T_j = 125 °C	–	–	4,5	mA
I_{GES}	V_{GE} = 20 V, V_{CE} = 0 V	–	–	400	nA
V_{CEsat}	I_C = 150 A } V_{GE} = 15 V;	–	3,4(4,5)	3,9(5)	V
V_{CEsat}	I_C = 200 A } T_j = 25 (125) °C	–	3,8(5,5)	–	V
g_{fs}	V_{CE} = 20 V, I_C = 150 A	54	–	–	S
C_{CHC}	per IGBT	–	–	200	pF
C_{ies}	} V_{GE} = 0	–	20	–	nF
C_{oes}	} V_{CE} = 25 V	–	2	–	nF
C_{res}	} f = 1 MHz	–	0,55	–	nF
L_{CE}		–	–	20	nH
$t_{d(on)}$	} V_{CC} = 1200 V	–	580	–	ns
t_r	} V_{GE} = + 15 V / - 15 V	–	100	–	ns
$t_{d(off)}$	} I_C = 150 A, ind. load	–	750	–	ns
t_f	} R_{Gon} = R_{Goff} = 4 Ω	–	40	–	ns
E_{on}	} T_j = 125 °C	–	95	–	mWs
E_{off}		–	45	–	mWs
Inverse Diode [8]					
V_F = V_{EC}	I_F = 150 A } V_{GE} = 0 V;	–	2,2(1,9)	2,7	V
V_F = V_{EC}	I_F = 200 A } T_j = 25 (125) °C	–	2,4(2,2)	–	V
V_{TO}	T_j = 125 °C	–	1,3	1,5	V
r_T	T_j = 125 °C	–	4,5	6,2	mΩ
I_{RR}	I_F = 150 A; T_j = 25 (125) °C[2]	–	60(85)	–	A
Q_{rr}	I_F = 150 A; T_j = 25 (125) °C[2]	–	15(38)	–	µC
FWD of types "GAL, GAR, D1 " [6) 8)]					
V_F = V_{EC}	I_F = 150 A } V_{GE} = 0 V;	–	2,0(1,8)	2,4	V
V_F = V_{EC}	I_F = 200 A } T_j = 25 (125) °C	–	2,2(2,0)	–	V
V_{TO}	T_j = 125 °C	–	1,3	1,5	V
r_T	T_j = 125 °C	–	3,5	4,5	mΩ
I_{RR}	I_F = 150 A; T_j = 25 (125) °C[2]	–	75(110)	–	A
Q_{rr}	I_F = 150 A; T_j = 25 (125) °C[2]	–	20(50)	–	µC
Thermal Characteristics					
R_{thjc}	per IGBT	–	–	0,1	°C/W
R_{thjc}	per diode D/"GAL, GAR, D1"	–	–	0,32/0,21	°C/W
R_{thch}	per module	–	–	0,038	°C/W

SEMITRANS® M IGBT Modules

SKM 200 GB 173 D
SKM 200 GB 173 D1 [6]
SKM 200 GAL 173 D [6]
SKM 200 GAR 173 D [6]

SEMITRANS 3



GB **GAL** **GAR**

Features

- MOS input (voltage controlled)
- N channel, Homogeneous Si
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 * I_{cnom}
- Latch-up free
- Fast & soft inverse CAL diodes[8]
- Isolated copper baseplate using DCB Direct Copper Bonding
- Large clearance (13 mm) and creepage distances (20 mm).

Typical Applications:

- AC inverter drives on mains 575 - 750 V_{AC}
- DC bus voltage 750 - 1200 V_{DC}
- Public transport (auxiliary syst.)
- Switching (not for linear use)

1) T_{case} = 25 °C, unless otherwise specified
2) I_F = – I_C, V_R = 1200 V, – di_F/dt = 1000 A/µs, V_{GE} = 0 V
6) The free-wheeling diodes of the GAL, GAR and D1 types have the data of the inverse diodes of SKM 300 GA 173 D
8) CAL = Controlled Axial Lifetime Technology.

Cases and mech. data → B6-258

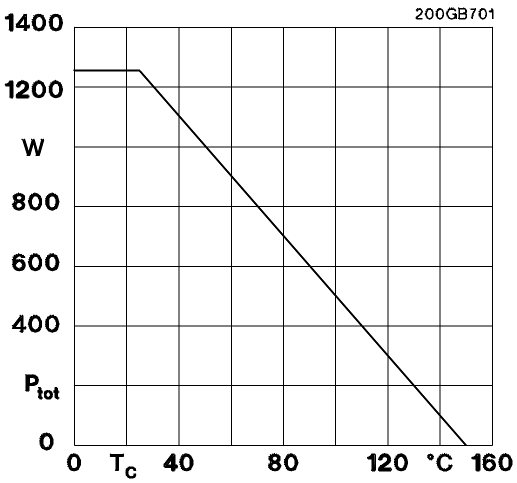
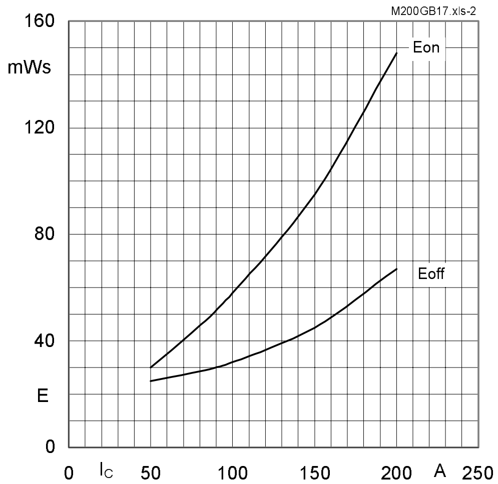
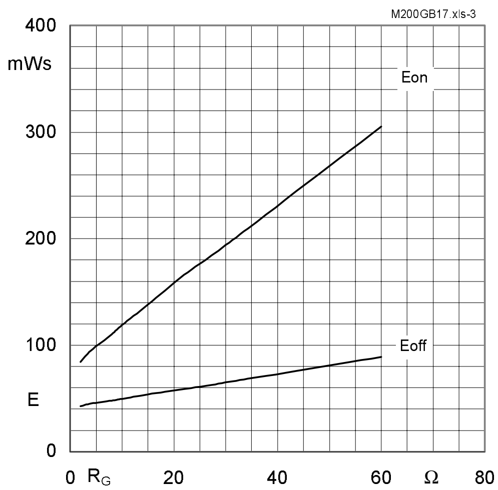


Fig. 1 Rated power dissipation P_{tot} = f (T_C)



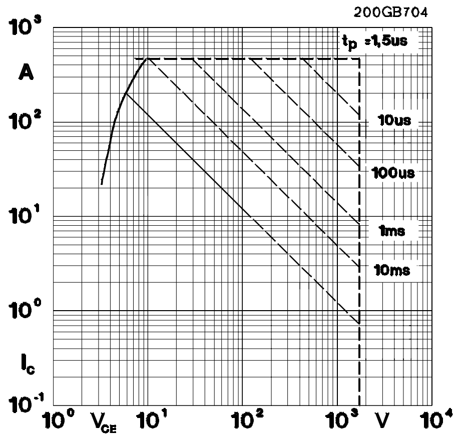
T_j = 125 °C
V_{CE} = 1200 V
V_{GE} = ± 15 V
R_G = 4 Ω

Fig. 2 Turn-on /-off energy = f (I_C)



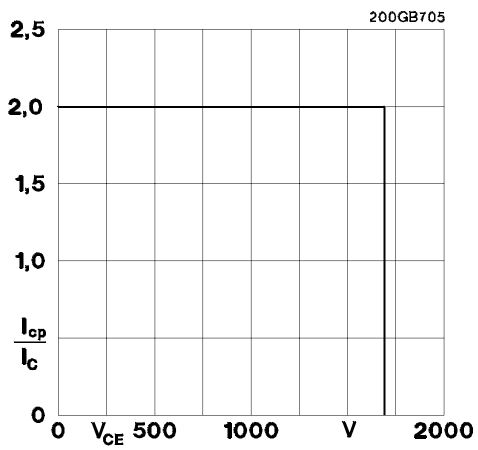
T_j = 125 °C
V_{CE} = 1200 V
V_{GE} = ± 15 V
I_C = 150 A

Fig. 3 Turn-on /-off energy = f (R_G)



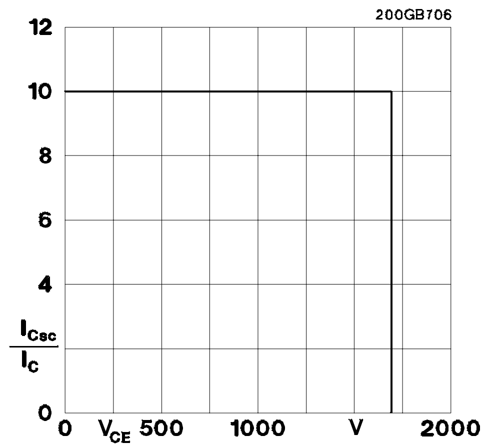
1 pulse
T_C = 25 °C
T_j ≤ 150 °C

Fig. 4 Maximum safe operating area (SOA) I_C = f (V_{CE})



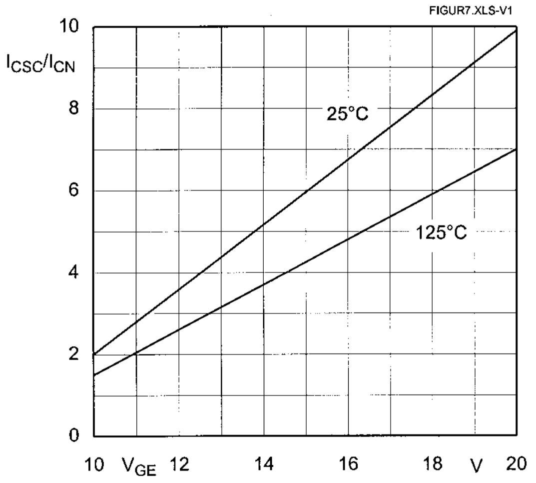
T_j ≤ 150 °C
V_{GE} = ± 15 V
R_{Goff} = 4 Ω
I_C = 150 A

Fig. 5 Turn-off safe operating area (RBSOA)



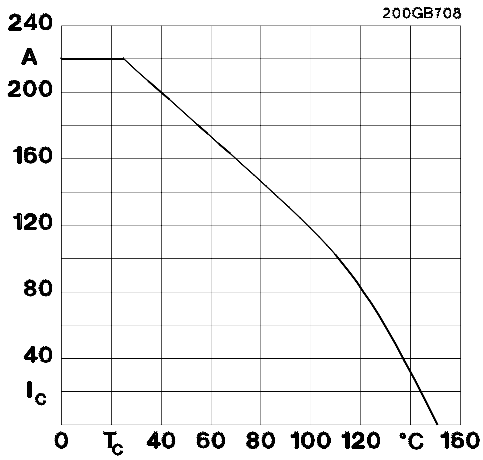
T_j ≤ 150 °C
V_{GE} = ± 15 V
t_{sc} ≤ 10 µs
L_{ext} < 50 nH
I_C = 150 A

Fig. 6 Safe operating area at short circuit I_C = f (V_{CE})



V_{CC} = 1200 V
I_C = 150 A
R_G = 4 Ω
$L_{ext} \leq$ 50 nH
self-limiting
t_p = 10 µs

Fig. 7 Short circuit current vs. turn-on gate voltage



T_j = 150 °C
$V_{GE} \geq$ 15 V

Fig. 8 Rated current vs. temperature I_C = f (T_C)

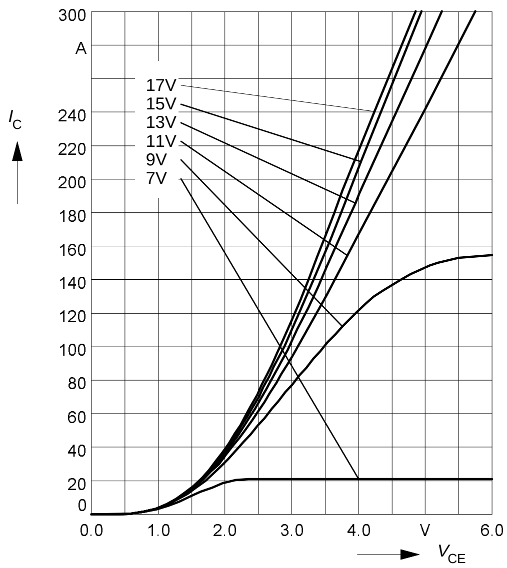


Fig. 9 Typ. output characteristic, t_p = 80 µs; T_j = 25 °C

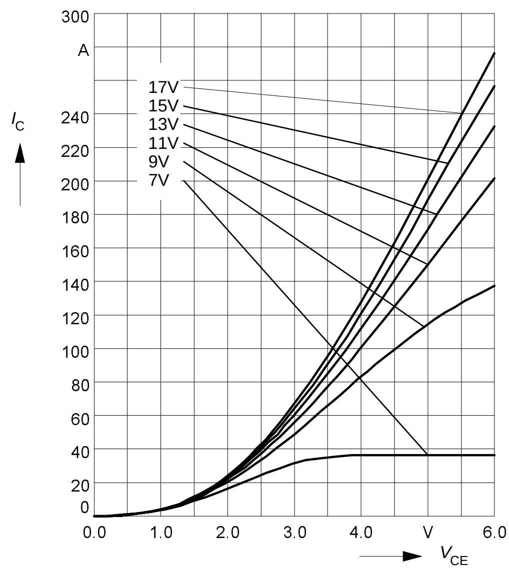


Fig. 10 Typ. output characteristic, t_p = 80 µs; T_j = 125 °C

$P_{cond(t)} = V_{CEsat(t)} \cdot I_{C(t)}$

$V_{CEsat(t)} = V_{CE(TO)(Tj)} + r_{CE(Tj)} \cdot I_{C(t)}$

$V_{CE(TO)(Tj)} \leq 1{,}9 + 0{,}003\ (T_j - 25)$ [V]

$r_{CE(Tj)} = 0{,}011 + 0{,}00004\ (T_j - 25)$ [Ω]

valid for $V_{GE} = +\,15\,^{+2}_{-1}$ [V]; $I_C \geq 0{,}3\ I_{Cnom}$

Fig. 11 Typ. saturation characteristic (IGBT)
Calculation elements and equations

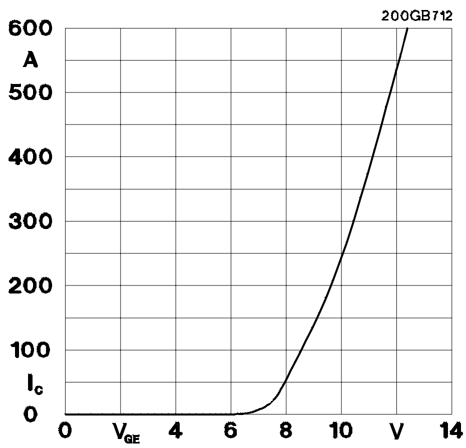
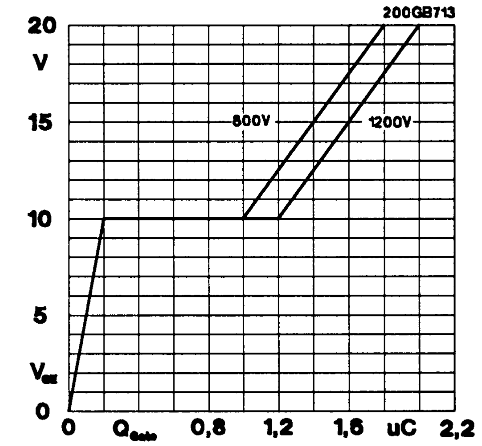


Fig. 12 Typ. transfer characteristic, t_p = 80 µs; V_{CE} = 20 V



I_{Cpuls} = 150 A

Fig. 13 Typ. gate charge characteristic

V_{GE} = 0 V
f = 1 MHZ

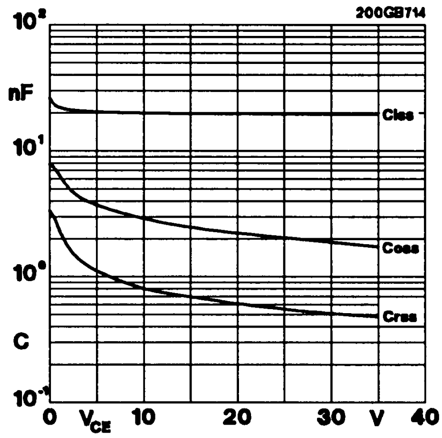
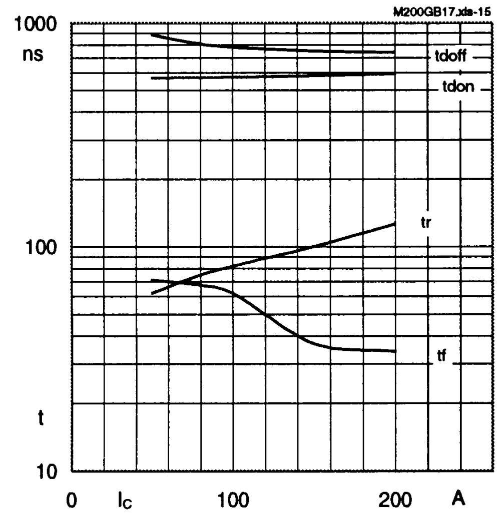
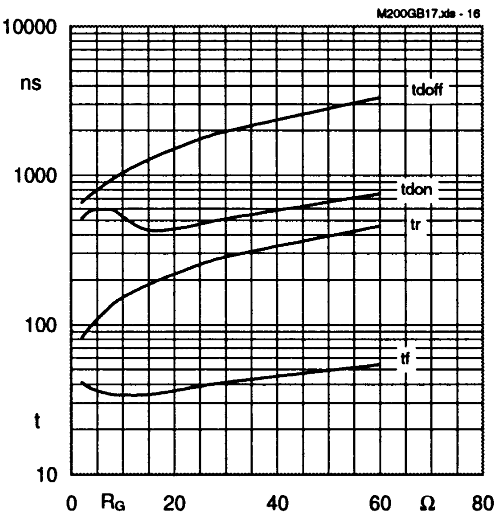


Fig. 14 Typ. capacitances vs.V_{CE}



T_j = 125 °C
V_{CC} = 1200 V
V_{GE} = ± 15 V
R_g = 4 Ω

Fig. 15 Typ. switching times vs. I_C



T_j = 125 °C
V_{CC} = 1200 V
V_{GE} = ± 15 V
I_C = 150 Ω

Fig. 16 Typ. switching times vs. R_G

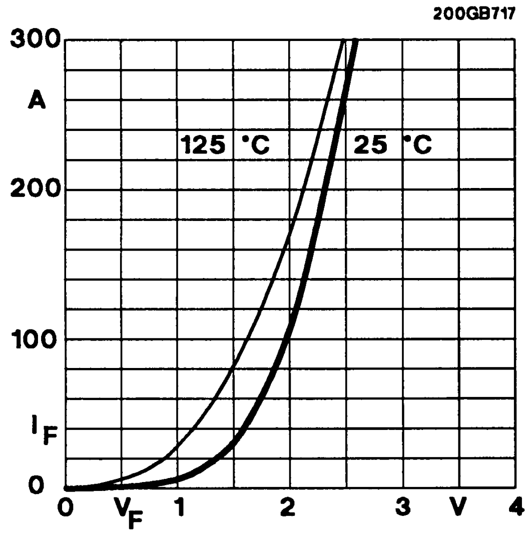


Fig. 17 Typ. CAL diode forward characteristic

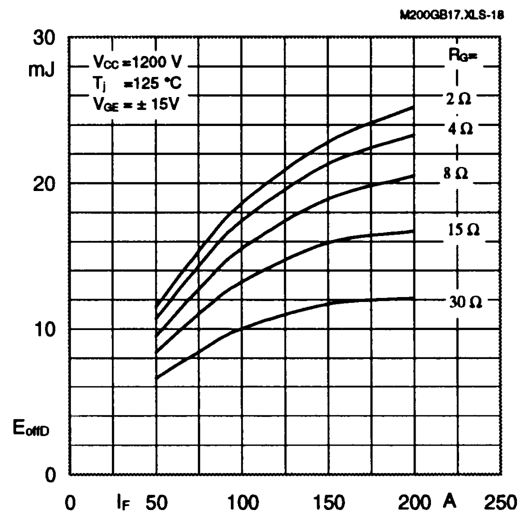


Fig. 18 Typ. Diode turn-off energy dissipation per pulse

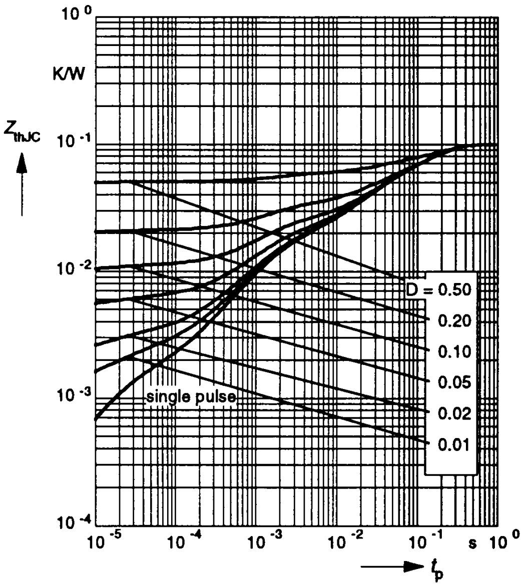


Fig. 19 Transient thermal impedance of IGBT: $Z_{thjc} = f(t_p)$; $D = t_p / t_c = t_p \cdot f$

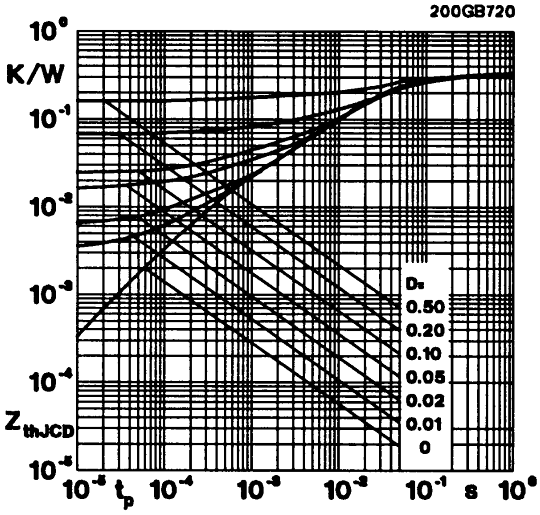


Fig. 20 Transient thermal impedance of inverse diode: $Z_{thjcD} = f(t_p)$

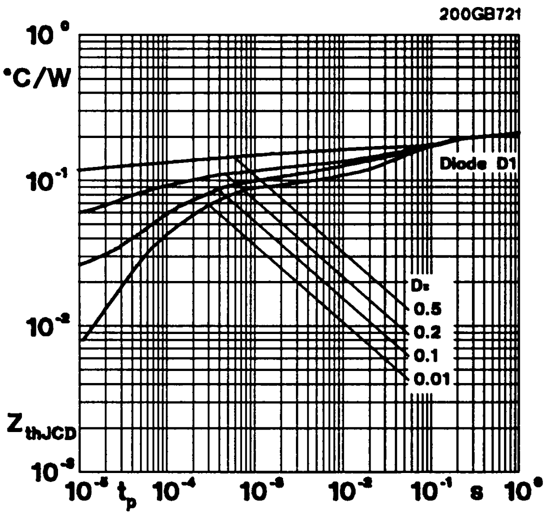


Fig. 21 Transient thermal impedance of FWD of SKM 200GAL173D: $Z_{thjcD} = f(t_p)$

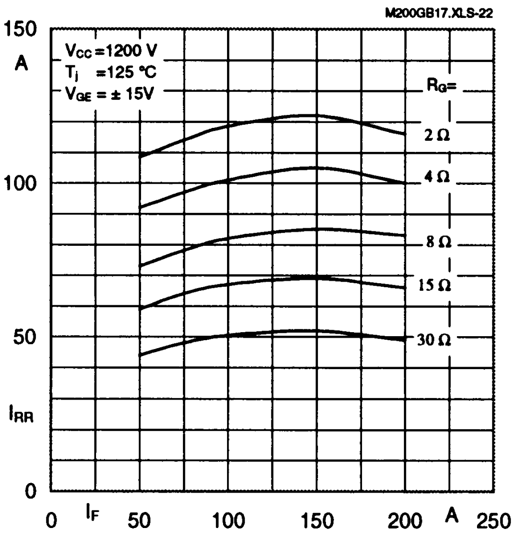


Fig. 22 Typ. CAL diode peak reverse recovery current of inverse diode $I_{RR} = f(I_F; R_G)$

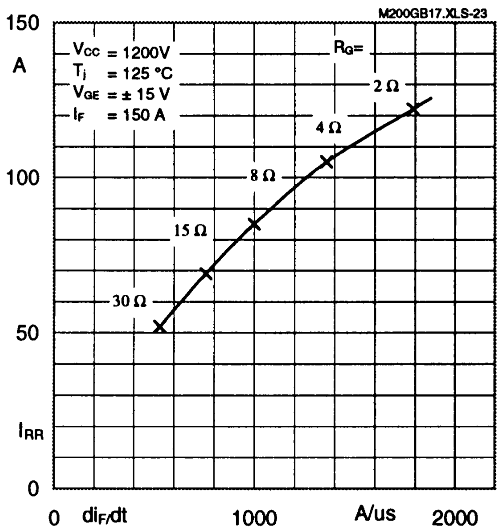


Fig. 23 Typ. CAL diode peak reverse recovery current of inverse diode: $I_{RR} = f(di_F/dt)$

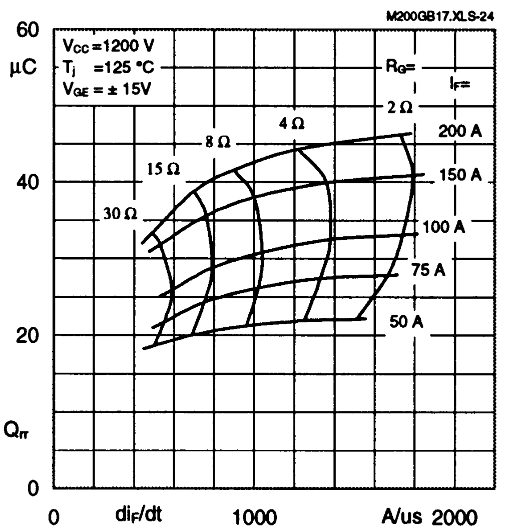


Fig. 24 Typ. CAL diode recovered charge Qrr of inverse diode

SEMITRANS 3

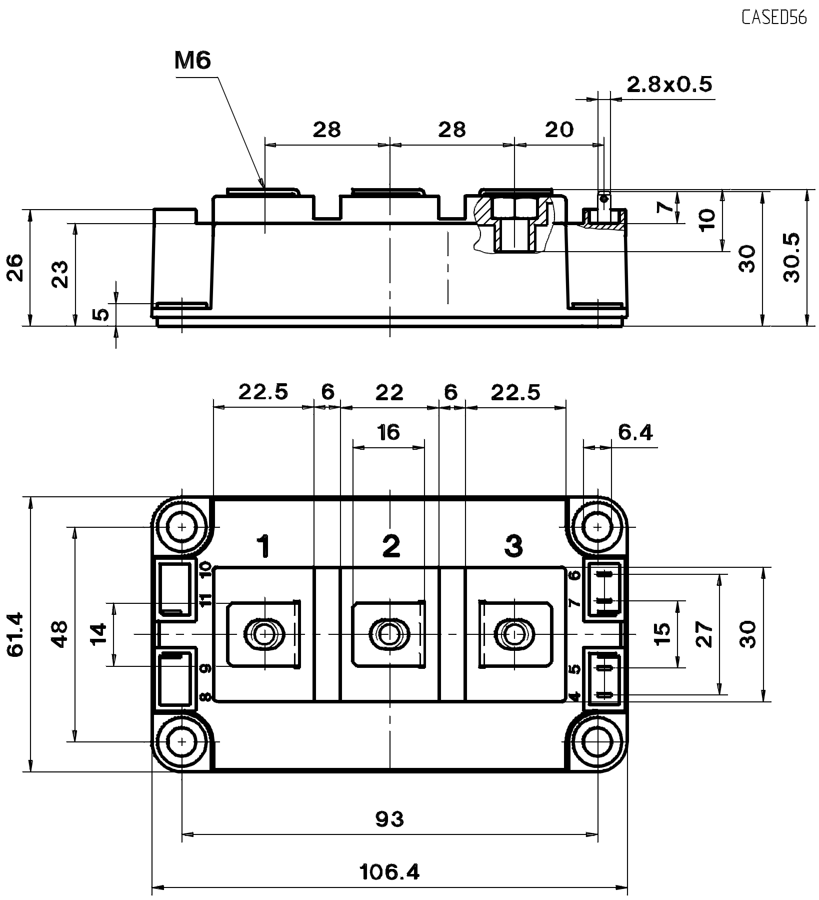
Case D 56

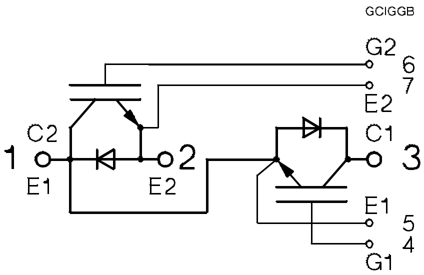
UL Recognized

File no. E 63 532

SKM 200 GB 123 D

SKM 200 GB 173 D



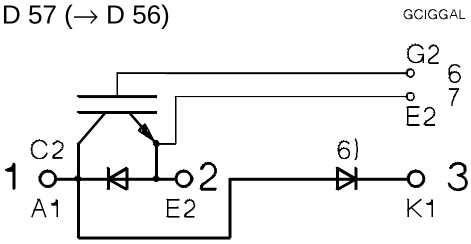


Dimensions in mm

SKM 150 GAL 123 D **SKM 200 GAL 123 D**

SKM 200 GAL 173 D

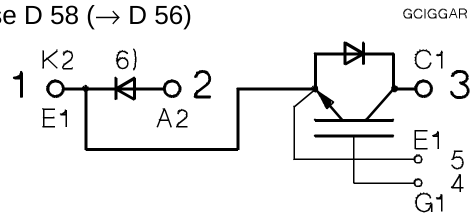
Case D 57 (→ D 56)



SKM 150 GAR 123 D **SKM 200 GAR 123 D**

SKM 200 GAR 173 D

Case D 58 (→ D 56)



Case outline and circuit diagrams

For SKM 200 GA 123 D (SEMITRANS 4) → B 6 - 168

Mechanical Data						
Symbol	**Conditions**		**Values**			**Units**
			min.	**typ.**	**max.**	
M_1	to heatsink, SI Units	(M6)	3	–	5	Nm
	to heatsink, US Units		27	–	44	lb.in.
M_2	for terminals, SI Units	(M6)	2,5	–	5	Nm
	for terminals US Units		22	–	44	lb.in.
a			–	–	5x9,81	m/s^2
w			–	–	325	g

This is an electrostatic discharge sensitive device (ESDS). Please observe the international standard IEC 747-1, Chapter IX.

Three devices are supplied in one SEMIBOX A without mounting hardware, which can be ordered separately under Ident No. 33321100 (for 10 SEMITRANS 3). Larger packing units of 12 and 20 pieces are used if suitable

Accessories → B 6 - 4.

SEMIBOX → C - 1.

6) Freewheeling diode → B 6 - 253, remark 6.

